

42390.P12897

PATENT



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Dias, et al.

Serial No.: 10/000,229

Filed: November 30, 2001

For: Backside Metallization On Sides Of
Microelectronic Dice For Effect
Thermal Contact With Heat
Dissipation Devices

Examiner: Hoai V. Pham

Group Art Unit: 2814


Attorney Docket No.: 42390P12897

Confirmation No.: 9231

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AMENDMENT

Commissioner for Patents
P.O. Box 1450
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Sir:

In response to the September 24, 2003 Office Action, please consider the following amendments and remarks.

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begin on page 3 of this paper.

Remarks/Arguments begin on page 11 of this paper